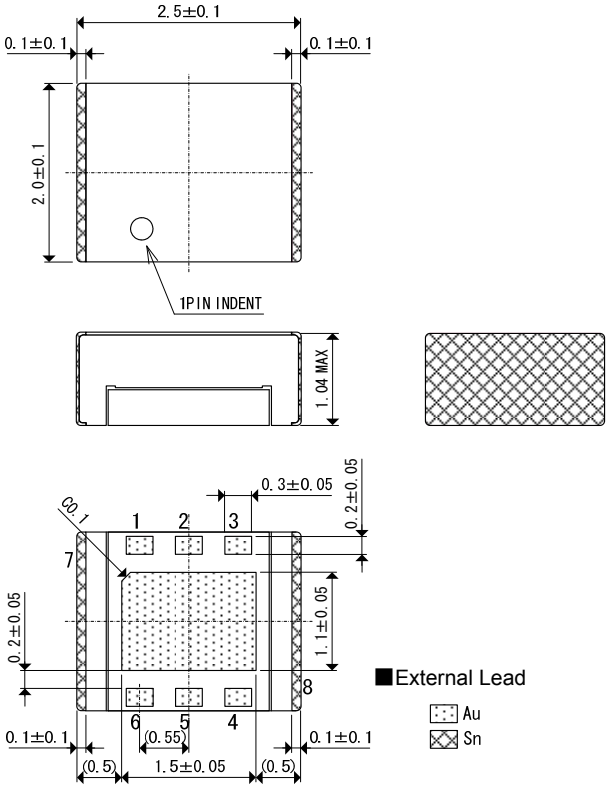
Packaging Information / Reference Pattern Layout Dimensions

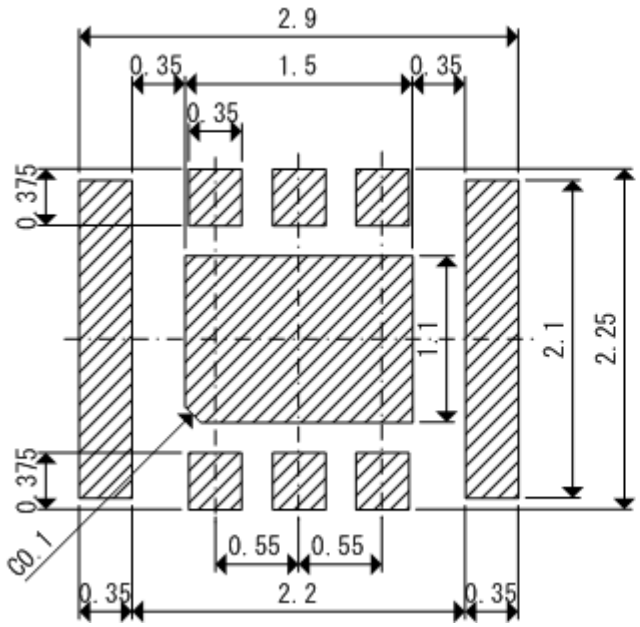
●CL-2025

Unit: mm

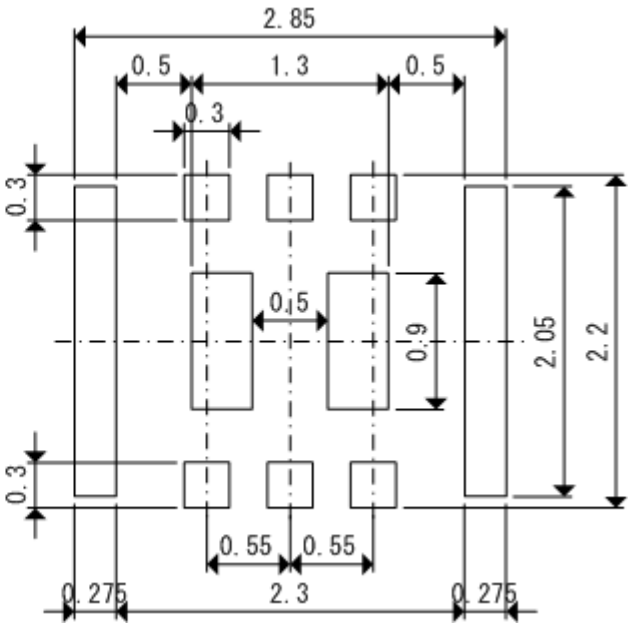
■Packaging Information



■Reference Pattern Layout Dimension



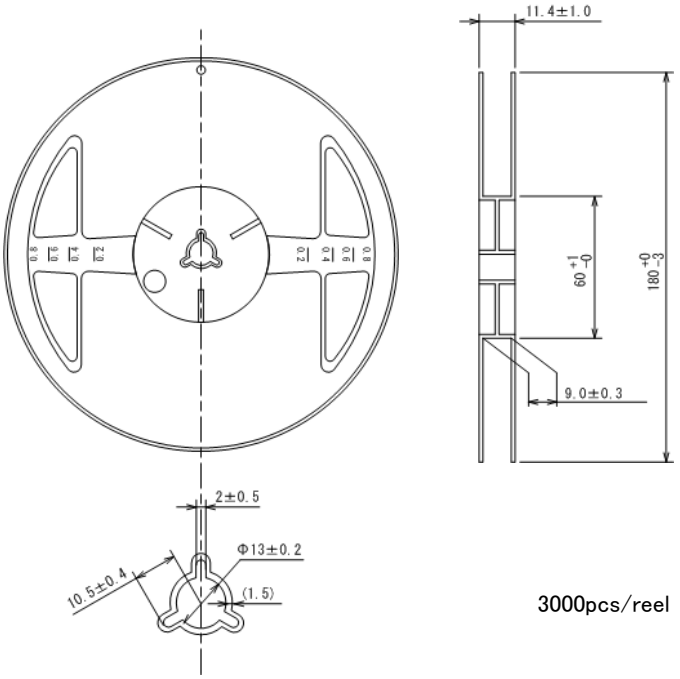
■Reference metal mask design



Taping Specifications

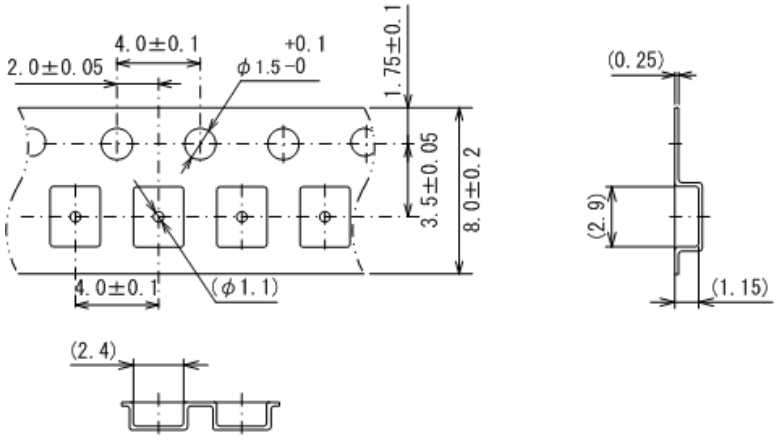
●CL-2025 Reel

Unit: mm

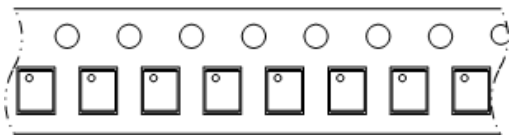


3000pcs/reel

●Taping Specifications



direction of feed



R Type :[Device orientation : Right]

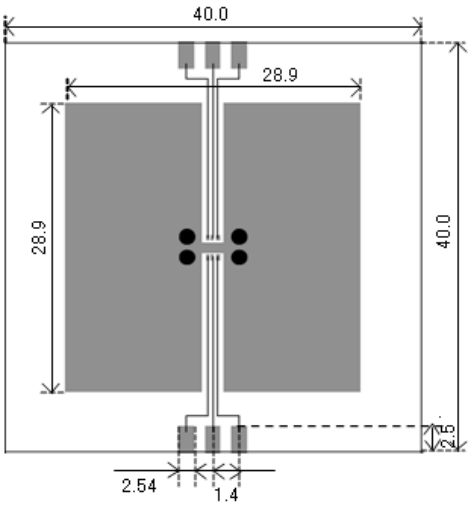
Standard feed

● CL-2025 Power Dissipation

Power dissipation data for the CL-2025 is shown in this page.
The value of power dissipation varies with the mount board conditions.
Please use this data as one of reference data taken in the described condition.

1. Measurement Condition (Reference data)

Condition: Mount on a board
Ambient: Natural convection
Soldering: Lead (Pb) free
Board: Dimensions 40 x 40 mm (1600 mm2 in one side)
Copper (Cu) traces occupy 50% of the board area
In top and back faces
Package heat-sink is tied to the copper traces
Material: Glass Epoxy (FR-4)
Thickness: 1.6 mm
Through-hole: 4 x 0.8 Diameter

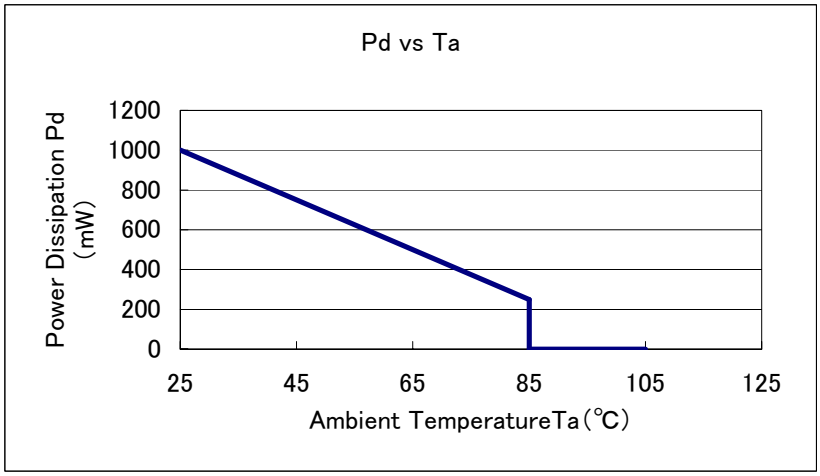


Evaluation Board (Unit: mm)

2. Power Dissipation vs. Ambient Temperature

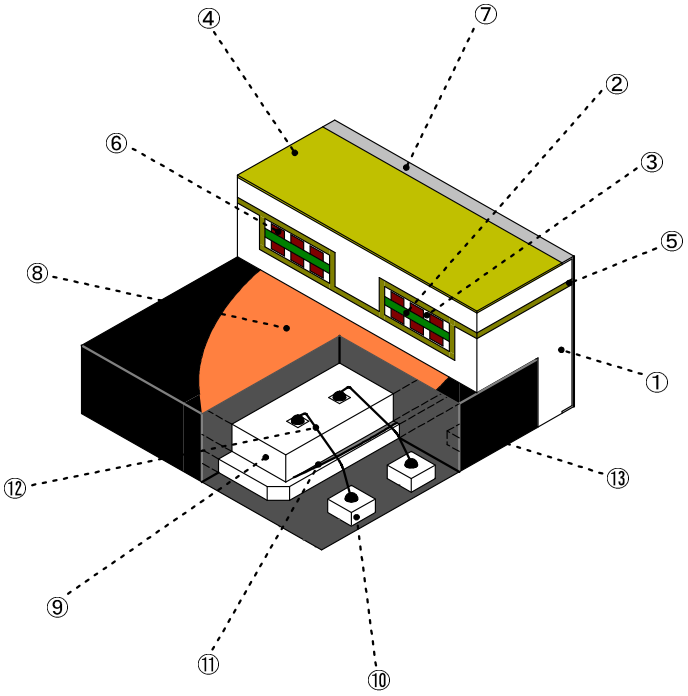
Board Mount (Tj max = 125℃)

Ambient Temperature(℃)	Power Dissipation Pd(mW)	Thermal Resistance(℃/W)
25	1000	100.00
85	250	



CL-2025 構造図
CL-2025 Perspective

RoHS対応品
RoHS Compliance



		項 目 Item	材 料 Material
コイル/Coil	①	コア Core	フェライト Ferrite
	②	ベース基板 Base Substrate	BTレジン+エポキシ樹脂 BT Resin + Epoxy Resin
	③	中間保護膜樹脂A Overcoating Resin A	エポキシ樹脂 Epoxy Resin
	④	保護膜樹脂B (トップコーティング) Overcoating Resin B (Top Coating)	
	⑤	接着樹脂 Adhesive Resin	
	⑥	導体(巻線部) Conductor	銅 Copper
	⑦	端子 Terminal	鉛フリーはんだメッキ，ニッケル Lead(Pb) free solder plating, Nickel
接着剤 Adhesive Resin	⑧	接着剤 Adhesive Resin	エポキシ樹脂 Epoxy Resin
IC	⑨	シリコンチップ Silicon Chip	シリコン Silicon
	⑩	リードパッド Lead-Pad	ニッケル, 金 Nickel，Gold Plating
	⑪	ダイアタッチ Die Attach	エポキシ Epoxy
	⑫	ボンディングワイヤ Bonding Wire	金 Au
	⑬	封止樹脂 Resin	エポキシ樹脂 Epoxy Resin

捺印表示 Marking	レーザー Laser Marking